

LEOCO CORPORATION		PRODUCTION SPECIFICATION		No.	S-90-9023	Rev.	2																																																					
9023 BOARD IN TERMINAL This specification describes the characteristics, test condition and particular sanctions applicable to LEOCO 9023 board in terminal, The subject product should meet the requirements when crimped onto the specified size wires. 1. Electrical performance 电气特性: <table><tr><td>ITEM</td><td>DESCRIPTION 内容</td><td>TEST CONDITION 测试条件</td><td>REQUIREMENT 需 求</td></tr><tr><td>1.1</td><td>Rated current 额定电流</td><td>When used max. size wire</td><td>Depend upon wire spec.</td></tr><tr><td>1.2</td><td>Contact Resistance 接触阻抗</td><td>Dry circuit of DC 50mV 50mA max</td><td>10 miliohms max.</td></tr></table> 2. Mechanical Performance 机械特性: <table><tr><td>ITEM</td><td>DESCRIPTION 内容</td><td>TEST CONDITION 测试条件</td><td>REQUIREMENT 需 求</td></tr><tr><td>2-1</td><td>Wire size 线材规格</td><td>Specified wire size</td><td>Accepts AWG#18 - #22</td></tr><tr><td rowspan="3">2-2</td><td rowspan="3">Terminal crimp strength 铆合张力强度</td><td>When crimped AWG#18 size wire</td><td>8.0Kg min.</td></tr><tr><td>When crimped AWG#20 size wire</td><td>6.0Kg min.</td></tr><tr><td>When crimped AWG#22 size wire</td><td>4.0Kg min.</td></tr><tr><td>2-3</td><td>Terminal insertion Force 端子插入力</td><td>Insertion speed 25+/- 3 mm per minute into specified hole on printed circuits board . (insertion force of crimped terminal)</td><td>3.0Kgf max.</td></tr><tr><td>2-4</td><td>Terminal removal Force 端子拔出力</td><td>removal speed 25+/- 3 mm per minute into specified hole on printed circuits board . (removal force of crimped terminal)</td><td>0.5Kgf min.</td></tr></table> 3. Environmental Performance 环境特性 : <table><tr><td>ITEM</td><td>DESCRIPTION 内容</td><td>TEST CONDITION 测试条件</td><td>REQUIREMENT 需 求</td></tr><tr><td>3-1</td><td>Solder ability 着锡性</td><td>Specimen shall be mounted on PCB. Solder temperature: 245±5 °C Immersion period: 5±0.5 sec.</td><td>Mininum:95% of Immersed area.</td></tr><tr><td>3-2</td><td>Resistance to Soldering heat 耐焊锡热</td><td>EIA-364-252 Solder temperature:260±5°C Immersion period:5±0.5sec.</td><td>No damage</td></tr><tr><td rowspan="2">3-3</td><td rowspan="2">Salt Spray 盐雾实验</td><td rowspan="2">EIA-364-26 Temperature: 35±2°C. Density: 5 % in weight. Period: 24 hours.</td><td>Appearance: No damage</td></tr><tr><td>Contact resistance: Less than twice of initial</td></tr></table>								ITEM	DESCRIPTION 内容	TEST CONDITION 测试条件	REQUIREMENT 需 求	1.1	Rated current 额定电流	When used max. size wire	Depend upon wire spec.	1.2	Contact Resistance 接触阻抗	Dry circuit of DC 50mV 50mA max	10 miliohms max.	ITEM	DESCRIPTION 内容	TEST CONDITION 测试条件	REQUIREMENT 需 求	2-1	Wire size 线材规格	Specified wire size	Accepts AWG#18 - #22	2-2	Terminal crimp strength 铆合张力强度	When crimped AWG#18 size wire	8.0Kg min.	When crimped AWG#20 size wire	6.0Kg min.	When crimped AWG#22 size wire	4.0Kg min.	2-3	Terminal insertion Force 端子插入力	Insertion speed 25+/- 3 mm per minute into specified hole on printed circuits board . (insertion force of crimped terminal)	3.0Kgf max.	2-4	Terminal removal Force 端子拔出力	removal speed 25+/- 3 mm per minute into specified hole on printed circuits board . (removal force of crimped terminal)	0.5Kgf min.	ITEM	DESCRIPTION 内容	TEST CONDITION 测试条件	REQUIREMENT 需 求	3-1	Solder ability 着锡性	Specimen shall be mounted on PCB. Solder temperature: 245±5 °C Immersion period: 5±0.5 sec.	Mininum:95% of Immersed area.	3-2	Resistance to Soldering heat 耐焊锡热	EIA-364-252 Solder temperature:260±5°C Immersion period:5±0.5sec.	No damage	3-3	Salt Spray 盐雾实验	EIA-364-26 Temperature: 35±2°C. Density: 5 % in weight. Period: 24 hours.	Appearance: No damage	Contact resistance: Less than twice of initial
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